

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

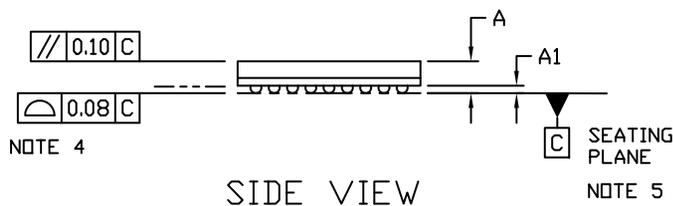
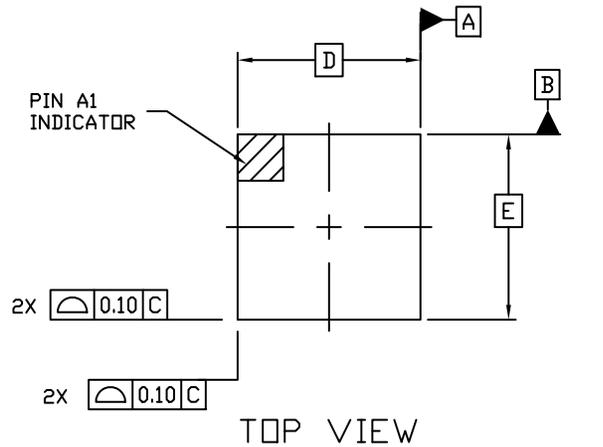
ON Semiconductor®



SCALE 2:1

LFBGA 57, 5x5
CASE 566AA
ISSUE B

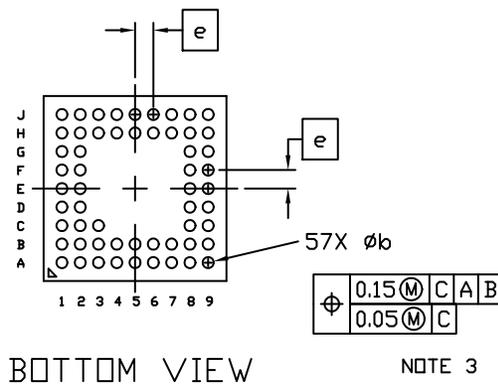
DATE 07 FEB 2012



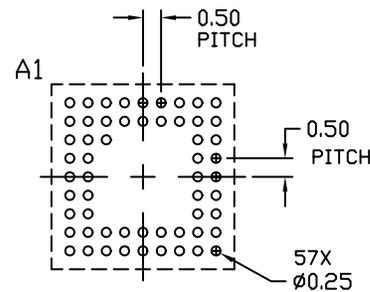
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION *b* IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS	
	MIN.	MAX.
A	0.76	0.96
A1	0.15	0.25
<i>b</i>	0.25	0.35
D	5.00 BSC	
E	5.00 BSC	
<i>e</i>	0.50 BSC	



RECOMMENDED MOUNTING FOOTPRINT



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DESCRIPTION:	LFBGA 57, 5X5	PAGE 1 OF 2

